

WHAT IS CLAIMED IS:

1. A chassis assembly designed to reduce electromagnetic radiation from entering or leaving the interior of the chassis assembly, comprising;

a chassis cover, the chassis cover comprising a hem assembly adapted to mate with a chassis back such that an interior surface of the chassis back is in secure physical contact with the chassis cover; and

wherein the hem assembly mated with the chassis back provides a tortuous path to any electromagnetic radiation disposed to enter or leave the chassis assembly.

2. The chassis assembly according to claim 1, wherein the tortuous path comprises:
a first bend of substantially 90 degrees, formed between by the hem assembly and a chassis back top portion; and

a second bend of substantially 90 degrees, formed by bending the chassis cover between a chassis cover pre-step portion and chassis cover step portion.

3. The chassis assembly according to claim 1, wherein the hem assembly comprises:
a chassis cover pre-step portion;
a hemmed lip, adapted to comprise one or more dimpled spring fingers;
a hemmed edge, which is a bending point, allowing the hemmed lip to be bent under the chassis cover pre-step portion at or about 180°, providing the dimpled spring fingers to engage an underside of the chassis cover.

4. The chassis assembly according to claim 1, further comprising:
one or more dimpled spring fingers; and
a chassis back top portion securely contacting the one or more dimpled spring fingers to provide good electrical conductivity between the chassis back and chassis cover.

5. A chassis cover used in a chassis assembly designed to reduce electromagnetic radiation from entering or leaving the interior of the chassis assembly, comprising:
a hem assembly, comprising a chassis cover pre-step portion, a hemmed lip, a hemmed

edge and one or more dimpled spring fingers; and

a chassis cover top portion, wherein a third bend is made between the chassis cover top portion and the chassis cover step portion, and a second bend is made between the chassis cover step portion and the chassis cover pre-step portion, and the hemmed lip is bent at the hemmed edge between the chassis cover pre-step portion and the hemmed lip to form a fifth bend, such that that one or more dimpled spring fingers located on an underside of the hemmed lip now point in a direction substantially perpendicular to a topside of the chassis cover pre-step portion and chassis cover top portion.

6. The chassis cover according to claim 5, wherein:

the third bend between the chassis cover top portion and the chassis cover step portion is at or about 90°.

7. The chassis cover according to claim 5, wherein:

the second bend between the chassis cover step portion and the chassis cover pre-step portion is at or about 90°.

8. The chassis cover according to claim 5, wherein:

the fifth bend at the hemmed edge is at or about 180°.

9. A method of manufacturing a chassis assembly, the chassis assembly designed to reduce electromagnetic interference, the method comprising:

forming a third bend between a chassis cover top portion and a chassis cover step portion;

forming a second bend between a chassis cover step portion and a chassis cover pre-step portion;

forming a fifth bend at a hemmed edge, wherein the hemmed edge resides between a hemmed lip, the hemmed lip comprising one or more dimpled spring fingers, and the chassis cover pre-step portion;

forming a fourth bend between a chassis back top portion and the chassis back, wherein a formed chassis cover comprises the chassis cover top portion, the chassis cover step portion, the

chassis cover pre-step portion, the hemmed edge, the hemmed lip and the one or more dimpled spring fingers; and

seating the formed chassis cover with the chassis back to create a tortuous path.

10. The method according to claim 9, wherein the step of seating the formed chassis cover with the chassis back comprises:

sliding the hemmed edge under the chassis back top portion formed from the chassis back, such that the one or more dimpled spring fingers is in contact with an underside of the chassis back top portion, providing good electrical conductivity.

11. The method according to claim 9, wherein:

the second, third and fourth bends are at or about 90°; and
the fifth bend is at or about 180°.

12. The method according to claim 10, wherein the tortuous path comprises:

a path formed by the second bend, the portion between the underside of the chassis back top portion and a top of the chassis cover pre-step portion, and a first bend formed by the union of the fourth bend and the hemmed edge.

13. The method according to claim 12, wherein:

the first bend is at or about 90°.